THROUGH SILICON VIA DIES AND PACKAGES

ABSTRACT

A method for preparing a die for packaging is disclosed. A die having first and second major surfaces is provided. Vias and a mask layer are formed on the first major surface of the die. The mask includes mask openings that expose the vias. The mask openings are filled with a conductive material. The method includes reflowing to at least partially fill the vias and contact openings to form via contacts in the vias and surface contacts in the mask openings.

Fig. 1